

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT

**CONVEYING PARTY DATA**

Name	Execution Date
NORIYUKI HAYASHIZAKA	08/19/2015
DAISUKE MISHOU	08/18/2015
TAKEO EBINA	09/24/2015
SATOMI HATTORI	08/20/2015
TAKAHIRO ISHIDA	08/20/2015
TOMOYUKI YAMAGUCHI	09/30/2015

**RECEIVING PARTY DATA**

<b>Name:</b>	SUMITOMO SEIKA CHEMICALS CO., LTD.
<b>Street Address:</b>	346-1, MIYANISHI
<b>City:</b>	HARIMA-CHO, KAKO-GUN, HYOGO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	675-0145
<b>Name:</b>	NATIONAL INSTITUTE OF ADVANCED INDUSTRIAL SCIENCE AND TECHNOLOGY
<b>Street Address:</b>	3-1, KASUMIGASEKI 1-CHOME
<b>City:</b>	CHIYODA-KU, TOKYO
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	100-8921
<b>Name:</b>	I&P CO., LTD.
<b>Street Address:</b>	1050-1, TAKASAKA
<b>City:</b>	HIGASHIMATSUYAMA-SHI, SAITAMA
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	355-0047

**PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	29533609

**CORRESPONDENCE DATA**

Fax Number: (202)293-7860

*Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent***PATENT**

*using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.*

**Phone:** 202-663-7387  
**Email:** ebarton@sughrue.com, sughrue@sughrue.com  
**Correspondent Name:** SUGHRUE MION, PLLC  
**Address Line 1:** 2100 PENNSYLVANIA AVE., NW, SUITE 800  
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<b>ATTORNEY DOCKET NUMBER:</b>	Q221123 (JTC)
<b>NAME OF SUBMITTER:</b>	ELAINE C. BARTON
<b>SIGNATURE:</b>	/Elaine C. Barton/
<b>DATE SIGNED:</b>	11/17/2015

**Total Attachments: 8**

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**ASSIGNMENT**

Whereas, I/we,

NameAddress

1) <b>Noriyuki HAYASHIZAKA</b>	c/o SUMITOMO SEIKA CHEMICALS CO., LTD., 346-1, Miyanishi, Harima-cho, Kako-gun, Hyogo 675-0145 Japan
2) <b>Daisuke MISHOU</b>	c/o SUMITOMO SEIKA CHEMICALS CO., LTD., 346-1, Miyanishi, Harima-cho, Kako-gun, Hyogo 675-0145 Japan
3) <b>Takeo EBINA</b>	c/o Tohoku Center, National Institute of Advanced Industrial Science and Technology, Nigatake 4-2-1, Miyagino-ku, Sendai-shi, Miyagi 983-8551 Japan
4) <b>Satomi HATTORI</b>	c/o SHIZUOKA INSTITUTE OF SCIENCE AND TECHNOLOGY, 2200-2, Toyosawa, Fukuroi-shi, Shizuoka 437-8555 Japan
5) <b>Takahiro ISHIDA</b>	c/o SHIZUOKA INSTITUTE OF SCIENCE AND TECHNOLOGY, 2200-2, Toyosawa, Fukuroi-shi, Shizuoka 437-8555 Japan
6) <b>Tomoyuki YAMAGUCHI</b>	c/o I&P CO., LTD., 1050-1, Takasaka, Higashimatsuyama-shi, Saitama 355-0047 Japan

hereinafter called assignor(s), have invented certain improvements in  
**Molded coil**

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on July 20, 2015, Serial No. 29/533609; and

Whereas

SUMITOMO SEIKA CHEMICALS CO., LTD.

346-1, Miyanishi,

Harima-cho, Kako-gun, Hyogo 675-0145 Japan

and, National Institute of Advanced Industrial Science and Technology

3-1, Kasumigaseki 1-chome,

Chiyoda-ku, Tokyo 100-8921 Japan

and, I&amp;P CO., LTD.

1050-1, Takasaka,

Higashimatsuyama-shi, Saitama 355-0047 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

INVENTORSDATE SIGNED

1) : Noriyuki Hayashizaka August 19, 2015  
Name : Noriyuki HAYASHIZAKA

2) : Daisuke Mishou August 18, 2015  
Name : Daisuke MISHOU

3) : \_\_\_\_\_  
Name : Takeo EBINA

4) : \_\_\_\_\_  
Name : Satomi HATTORI

5) : \_\_\_\_\_  
Name : Takahiro ISHIDA

6) : \_\_\_\_\_  
Name : Tomoyuki YAMAGUCHI

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1) : \_\_\_\_\_  
Name : Noriyuki HAYASHIZAKA

2) : \_\_\_\_\_  
Name : Daisuke MISHOU

3) : Takeo Ebina September 24, 2015  
Name : Takeo EBINA

4) : \_\_\_\_\_  
Name : Satomi HATTORI

5) : \_\_\_\_\_  
Name : Takahiro ISHIDA

6) : \_\_\_\_\_  
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5) Takahiro ISHIDA	c/o SHIZUOKA INSTITUTE OF SCIENCE AND TECHNOLOGY, 2200-2, Toyosawa, Fukuroi-shi, Shizuoka 437-8555 Japan
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1) :  
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2) :  
Name : Daisuke MISHOU

3) :  
Name : Takeo EBINA

4) :  
Name : *Satomi Hattori*  
Satomi HATTORI *Aug. 20, 2015*

5) :  
Name : *Takahiro Ishida*  
Takahiro ISHIDA *Aug. 20, 2015*

6) :  
Name : Tomoyuki YAMAGUCHI



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INVENTORS

DATE SIGNED

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Name : Noriyuki HAYASHIZAKA

2) : \_\_\_\_\_  
Name : Daisuke MISHOU

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Name : Takahiro ISHIDA

6) : *Tomoyuki Yamaguchi* \_\_\_\_\_  
Name : Tomoyuki YAMAGUCHI

\_\_\_\_\_ *Sep 30. 2015* \_\_\_\_\_